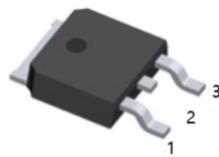


## General Description

The AOD407 uses advanced trench technology to provide excellent RDS(ON), low gate charge and low gate resistance. With the excellent thermal resistance of the TO-252 package, this device is well suited for high current load applications.



1.G      2.D      3.S  
TO-252(DPAK) top view

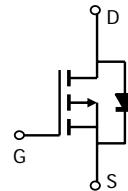
## Features

$V_{DS}$  (V) = -60V

$I_D$  = -12A ( $V_{GS}$  = -10V)

$R_{DS(ON)}$  < 115mΩ ( $V_{GS}$  = -10V)

$R_{DS(ON)}$  < 150mΩ ( $V_{GS}$  = -4.5V)



## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum		Units
Drain-Source Voltage	$V_{DS}$	-60		V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		V
Continuous Drain Current <sup>G</sup>	$I_D$	-12		A
$T_C=100^\circ\text{C}$		-10		
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	-30		
Avalanche Current <sup>C</sup>	$I_{AR}$	-12		A
Repetitive avalanche energy $L=0.1\text{mH}^C$	$E_{AR}$	23		mJ
Power Dissipation <sup>B</sup>	$P_D$	50		W
$T_C=100^\circ\text{C}$		25		
Power Dissipation <sup>A</sup>	$P_{DSM}$	2.5		W
$T_A=70^\circ\text{C}$		1.6		
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175		°C
Thermal Characteristics				
Parameter	Symbol	Typ	Ma	Units
Maximum Junction-to-Ambient	$R_{\theta JA}$	16.7	25	°C/W
Maximum Junction-to-Ambient		40	50	°C/W
Maximum Junction-to-Case <sup>B</sup>	$R_{\theta JC}$	2.5	3	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-60			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-48\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$		-0.003	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			$\pm100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.5	-2.1	-3	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	-30			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-12\text{A}$		91	115	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-8\text{A}$		114	150	$\text{m}\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-12\text{A}$		12.8		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.76	-1	V
$I_S$	Maximum Body-Diode Continuous Current				-12	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-30\text{V}, f=1\text{MHz}$		987	1185	pF
$C_{\text{oss}}$	Output Capacitance			114		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			46		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		7	10	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}, V_{DS}=-30\text{V}, I_D=-12\text{A}$		15.8	20	nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)			7.4	9	nC
$Q_{\text{gs}}$	Gate Source Charge			3		nC
$Q_{\text{gd}}$	Gate Drain Charge			3.5		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=-10\text{V}, V_{DS}=-30\text{V}, R_L=2.5\Omega, R_{\text{GEN}}=3\Omega$		9		ns
$t_r$	Turn-On Rise Time			10		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			25		ns
$t_f$	Turn-Off Fall Time			11		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=-12\text{A}, dI/dt=100\text{A}/\mu\text{s}$		27.5	35	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=-12\text{A}, dI/dt=100\text{A}/\mu\text{s}$		30		nC

A: The value of  $R_{\text{JJA}}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The Power dissipation  $P_{\text{DSM}}$  is based on  $R_{\text{JJA}}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design, and the maximum temperature of  $175^\circ\text{C}$  may be used if the PCB allows it.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=175^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=175^\circ\text{C}$ .

D. The  $R_{\text{JJA}}$  is the sum of the thermal impedance from junction to case  $R_{\text{JJC}}$  and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using  $<300\ \mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=175^\circ\text{C}$ .

G. The maximum current rating is limited by bond-wires.

H. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

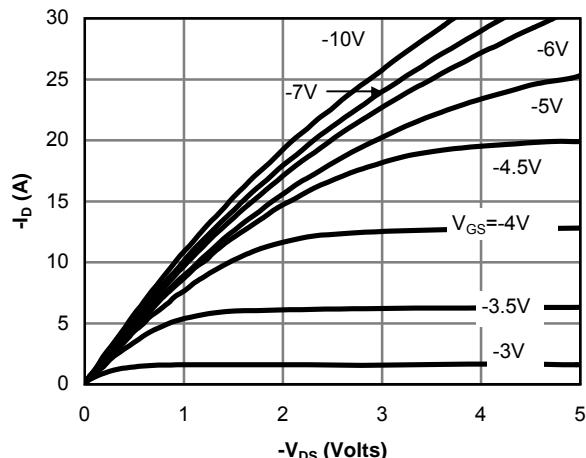


Fig 1: On-Region Characteristics

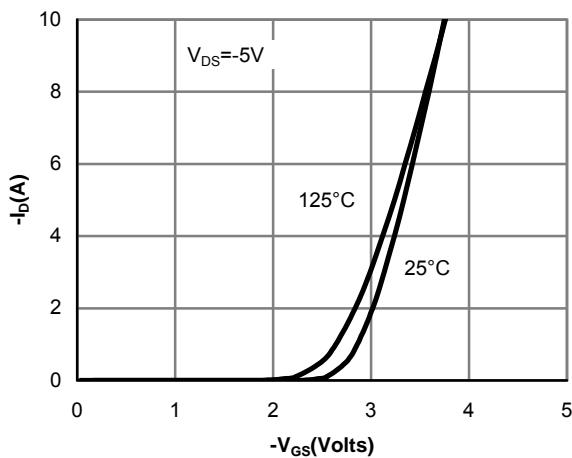


Figure 2: Transfer Characteristics

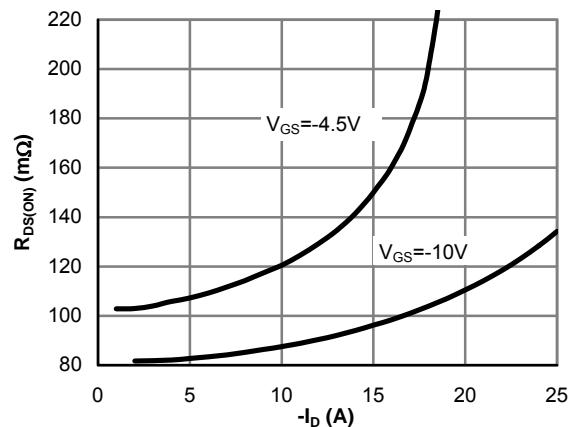


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

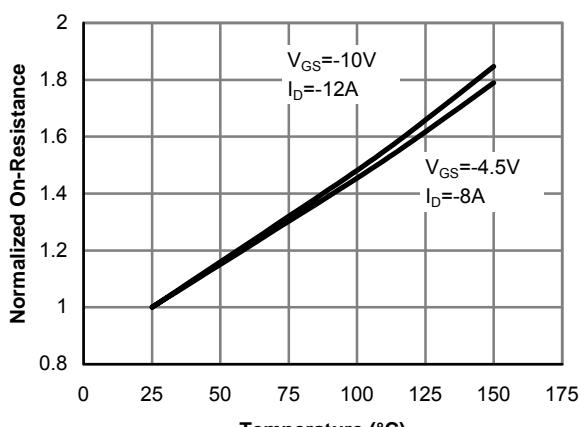


Figure 4: On-Resistance vs. Junction Temperature

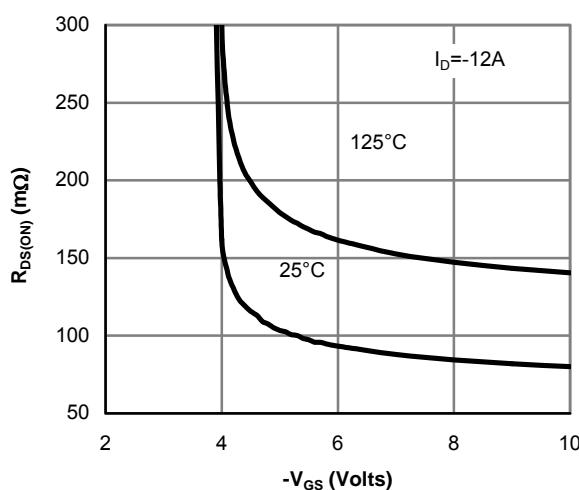


Figure 5: On-Resistance vs. Gate-Source Voltage

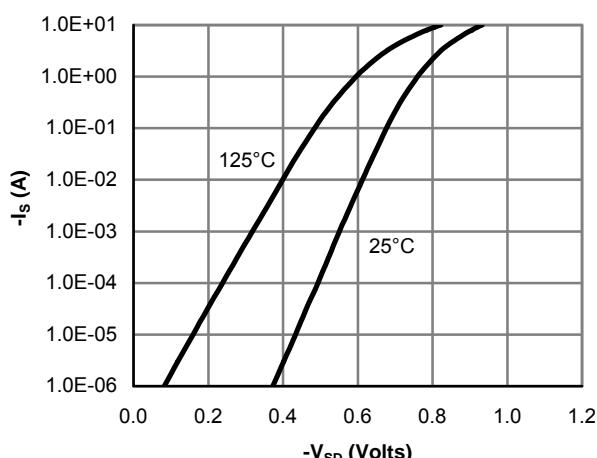
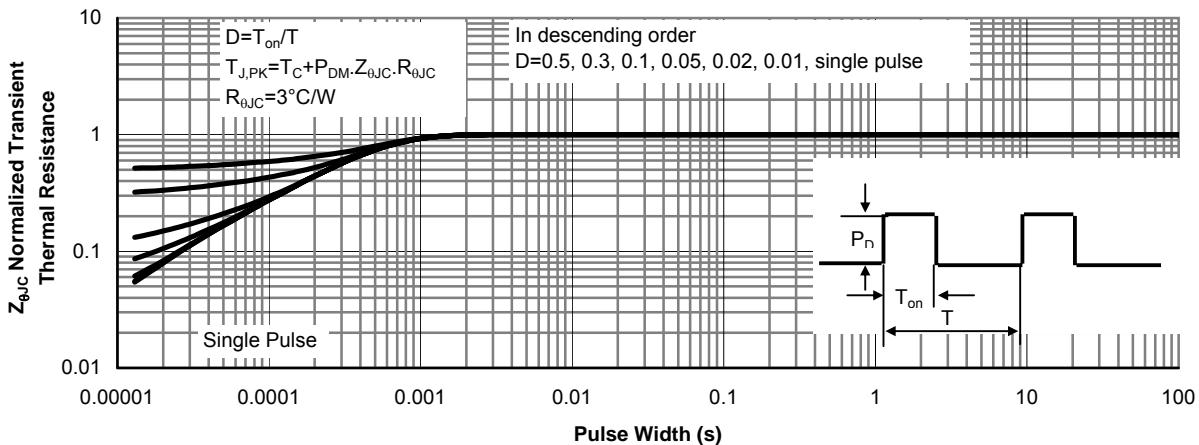
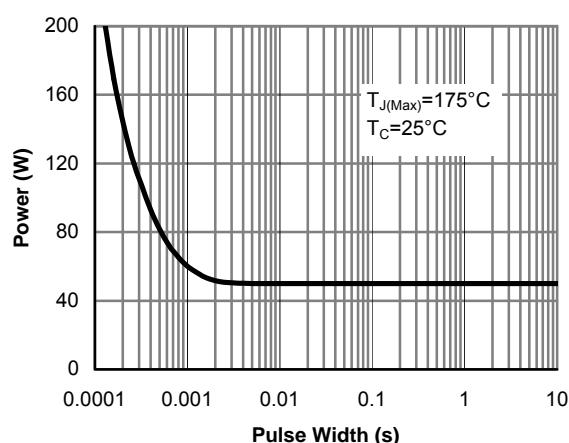
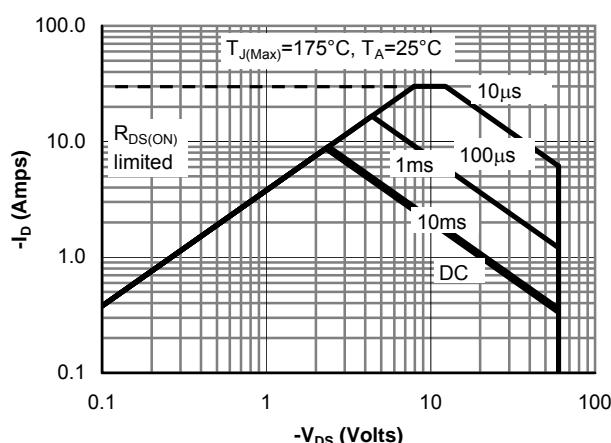
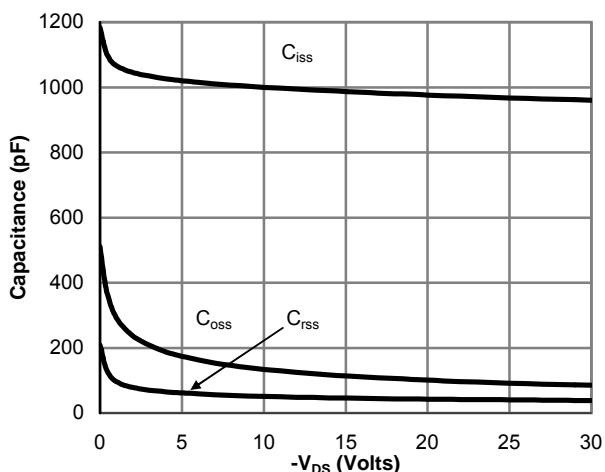
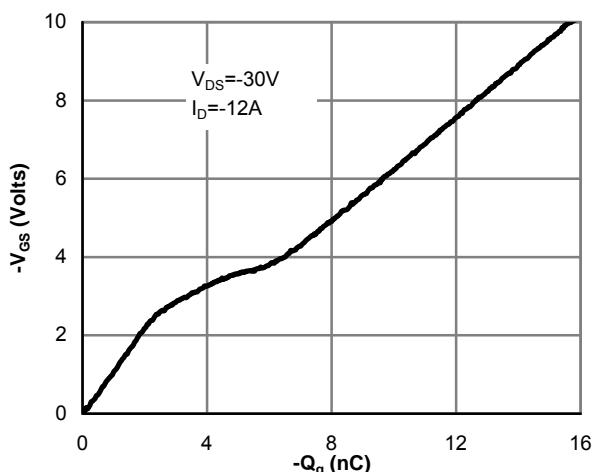


Figure 6: Body-Diode Characteristics

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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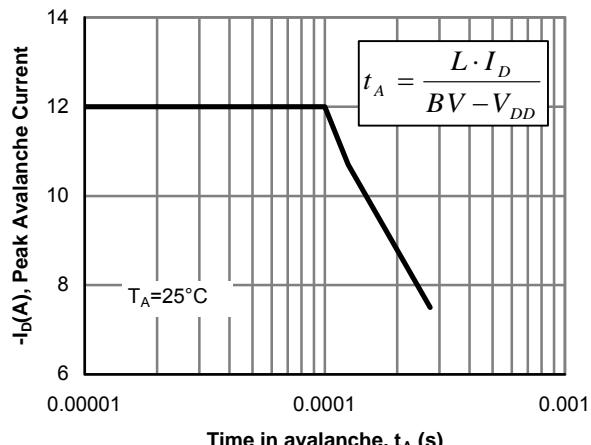


Figure 12: Single Pulse Avalanche capability

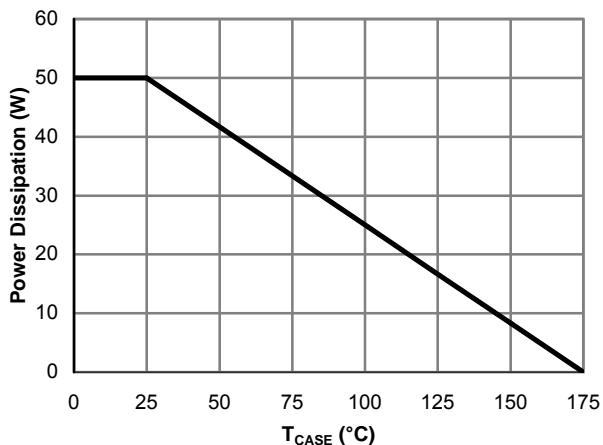


Figure 13: Power De-rating (Note B)

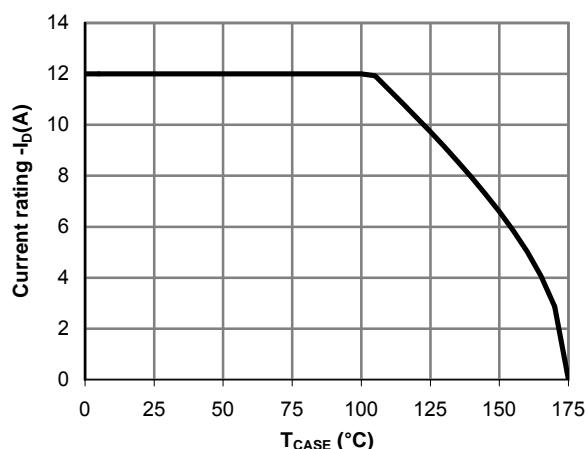


Figure 14: Current De-rating (Note B)

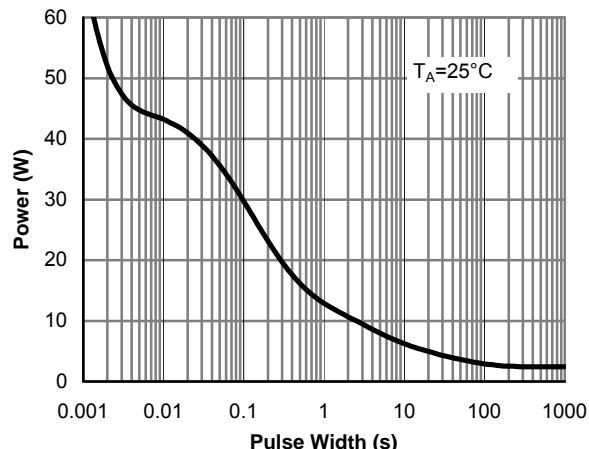


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

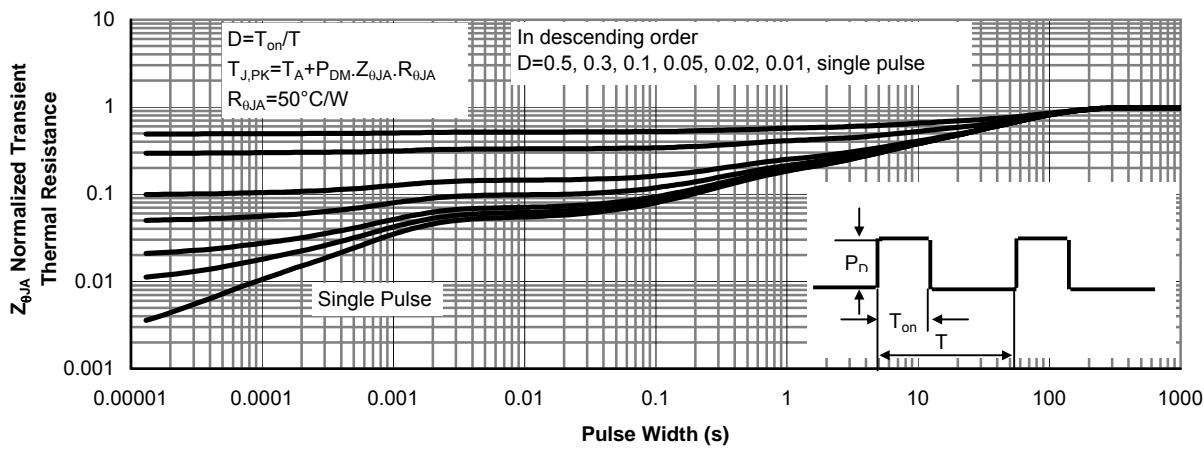
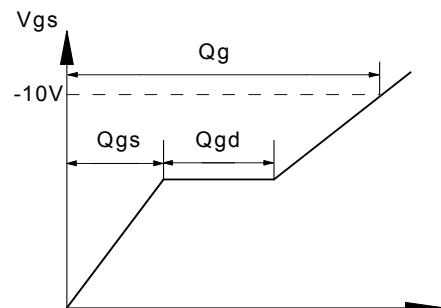
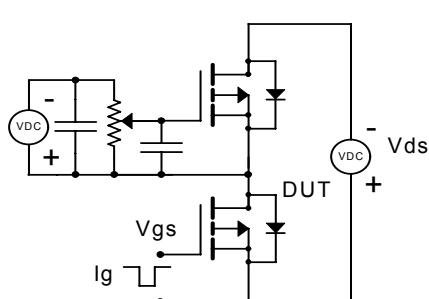
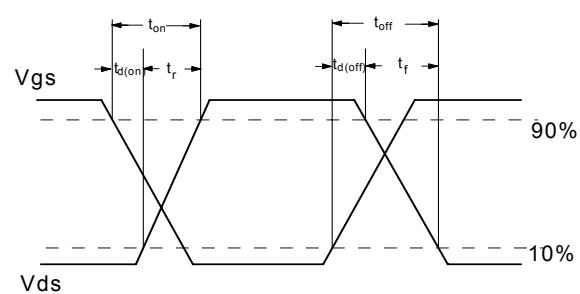
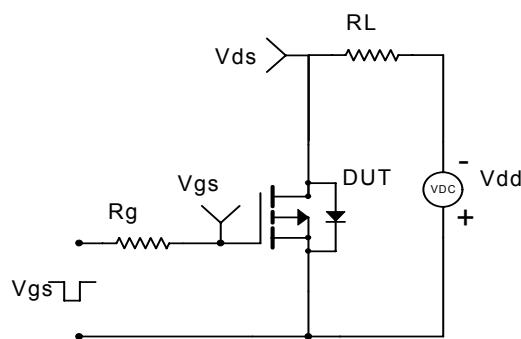


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

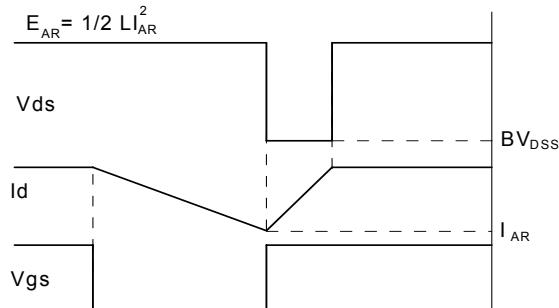
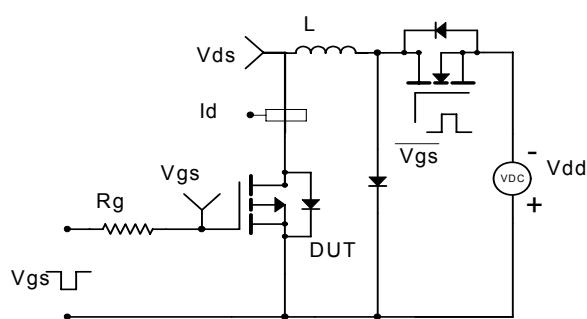
Gate Charge Test Circuit & Waveform



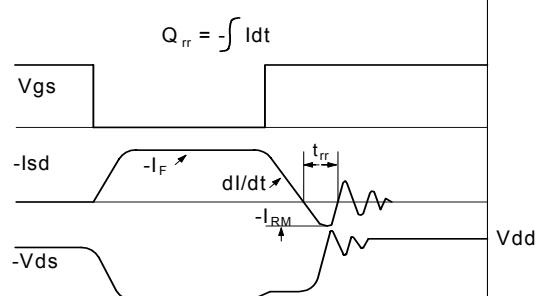
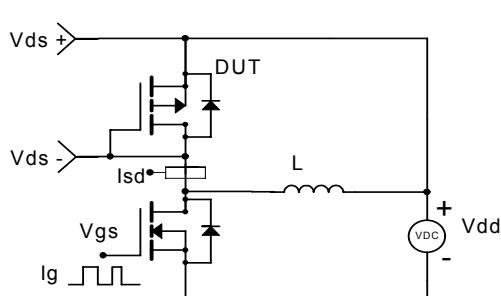
Resistive Switching Test Circuit & Waveforms



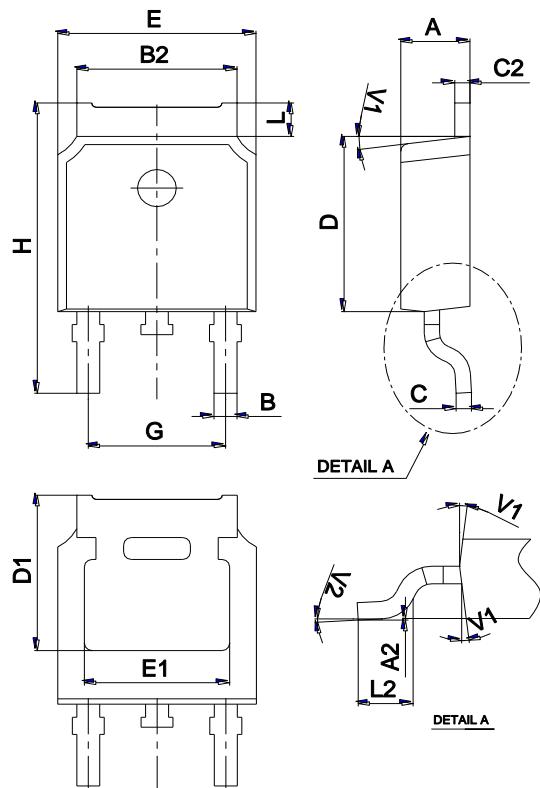
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

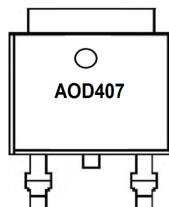


### Package Mechanical Data TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

### Marking



### Ordering information

Order code	Package	Baseqty	Deliverymode
AOD407	TO-252	2500	Tape and reel